Awards and Honors
Georgia Tech faculty and staff receive recognition.

Ali Adibi, an assistant professor in the School of Electrical and Computer Engineering, received the SPIE (International Society for Optical Engineering) Young Investigator Award in the area of Optoelectronics for his invited paper. Titled "Gated Holography: Materials, Techniques, and Applications," it was co-authored by Omid Momtahan and Arash Karbaschi.

Robert Fulton, a professor in the School of Mechanical Engineering, was selected as Engineer of the Year in Education by the Georgia Engineering Alliance and the Georgia Engineers Week Committee.

Tom Kurfess, a professor in the School of Mechanical Engineering, received the 2002 ASME/Pi Tau Sigma Gustus L. Larson Award. It honors demonstrated achievement in mechanical engineering within 10 to 20 years of graduation.

James D. Meindl, a professor in the School of Electrical and Computer Engineering, was named as one of the top 10 contributing authors/co-authors of IEEE Solid State Circuits Society Conference (ISSCC) papers during the past 50 years. Meindl published his first paper with the ISSCC in 1966.

Sue Rosser, dean of the Ivan Allen College, was recognized by the American Association for the Advancement of Science (AAAS) and the Association for Women in Science (AWIS). She was cited for "distinguished leadership in research on the theoretical and applied issues for women in science and for service to the science education community.
on curricular and classroom techniques to attract and retain women and minorities in science and engineering."

William Singhose, an assistant professor of mechanical engineering, received the 2003 Jiri Tlusty Outstanding Young Manufacturing Engineering Award from the Society of Manufacturing Engineers.

Suresh Sitaraman, an associate professor of mechanical engineering, received the best paper award for the second year in a row at the IEEE Transactions on Components and Packaging Technologies conference.

I. Charles Ume, a professor of mechanical engineering,

received the 2002 Donald P. Eckman Education Award from the Instrumentation, Systems and Automation Society. The award honors outstanding contributions in the pioneering and education of mechatronics.

Robert Nerem, professor of mechanical engineering and director of the Parker H. Petit Institute of Bioengineering and Bioscience, received the Pierre Galletti Award from the AIMBE Board of Directors. The award recognizes contributions to public awareness of biological and medical engineering and the promotion of a national interest in science, engineering and education.

Steve Usselman's recent book, *Regulating Railroad Innovation: Business, Technology and Politics in America, 1840-1920* (Cambridge University Press) was selected by the Organization of American Historians (OAH) as winner of the 2003 Ellis W. Hawley Prize. Usselman, an associate professor in the School of History, Technology and Society received the award honoring the year's best book published in the history of political economy, politics or institutions of the United States, domestic or international, from the Civil War to the present.

Ray Vito, associate dean of the College of Engineering and professor of mechanical engineering, received the 2002 Wallace H. Coulter Award for Innovation and Entrepreneurship. The award recognizes a technical achievement likely to have a significant impact on health care delivery.

C.P. Wong, a Regents' Professor in the School of Materials Science and Engineering, and his Ph.D. student Z. Zhang received the IEEE/ECA's 51st Electronic Components and
Technology Conference Outstanding Paper Award. Their award recognized a paper titled "Double Layer No-Flow Underfill Incorporated with Silica for Flip Chip Applications." Wong also received the IEEE Components Packaging and Manufacturing Technology Society's Exceptional Technical Achievement Award. He was recognized for his pioneering work in polymeric materials for electronic packaging applications and for the introduction and development of silicon gels to achieve reliability without hermeticity in plastic IC packaging.